1. In a heat pipe in which a boundary structure forms an enclosed vapor chamber, the improvement comprising: at least one mounting hole penetrating the heat pipe.

2. In a heat pipe in which a boundary structure forms an enclosed vapor chamber, the improvement comprising: at least one mounting hole penetrating the heat pipe, with the mounting hole isolated from the vapor chamber by being located within a sealed structure which is sealed to the boundary structure so that the mounting hole through the heat pipe has no access to the vapor chamber.

3. The heat pipe of claim 2 wherein the sealed structure is a column spanning the boundary structure.

4. The heat pipe of claim 2 wherein the sealed structure is a depression within one part of the boundary structure which contacts and is bonded to another part of the boundary structure.

5. The heat pipe of claim 2 wherein the sealed structure is a lip located at an edge of the boundary structure which is bonded to another lip at the edge of the boundary structure.

6. In a heat pipe in which a boundary structure forms an enclosed vapor chamber, with a capillary wick within the heat pipe attached to the part of the heat pipe which is in contact with a heat source, so that the capillary wick acts as the heat pipe evaporator, the improvement comprising: the capillary wick

being constructed with at least two separate sections of different materials and with a section located at the part of the heat pipe which is in contact with the heat source being formed of a material with higher heat conductivity than sections located at parts of the heat pipe not in contact with the heat source.

7. The heat pipe of claim 6 wherein the section of higher heat conductivity is constructed of sintered silver powder.